

# SOT1574-1

plastic, thermally enhanced quad flat non-leaded package; 16 terminals; 1.0 mm pitch; 6 mm x 6 mm x 1.98 mm body

9 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HQFN16
<b>Package type industry code</b>	HQFN16
<b>Package style descriptive code</b>	HQFN (thermal enhanced quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	06-01-2016
<b>Manufacturer package code</b>	98ASA00090D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
seated height	1.93	1.98	2.03	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	16	-	



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2 Package outline

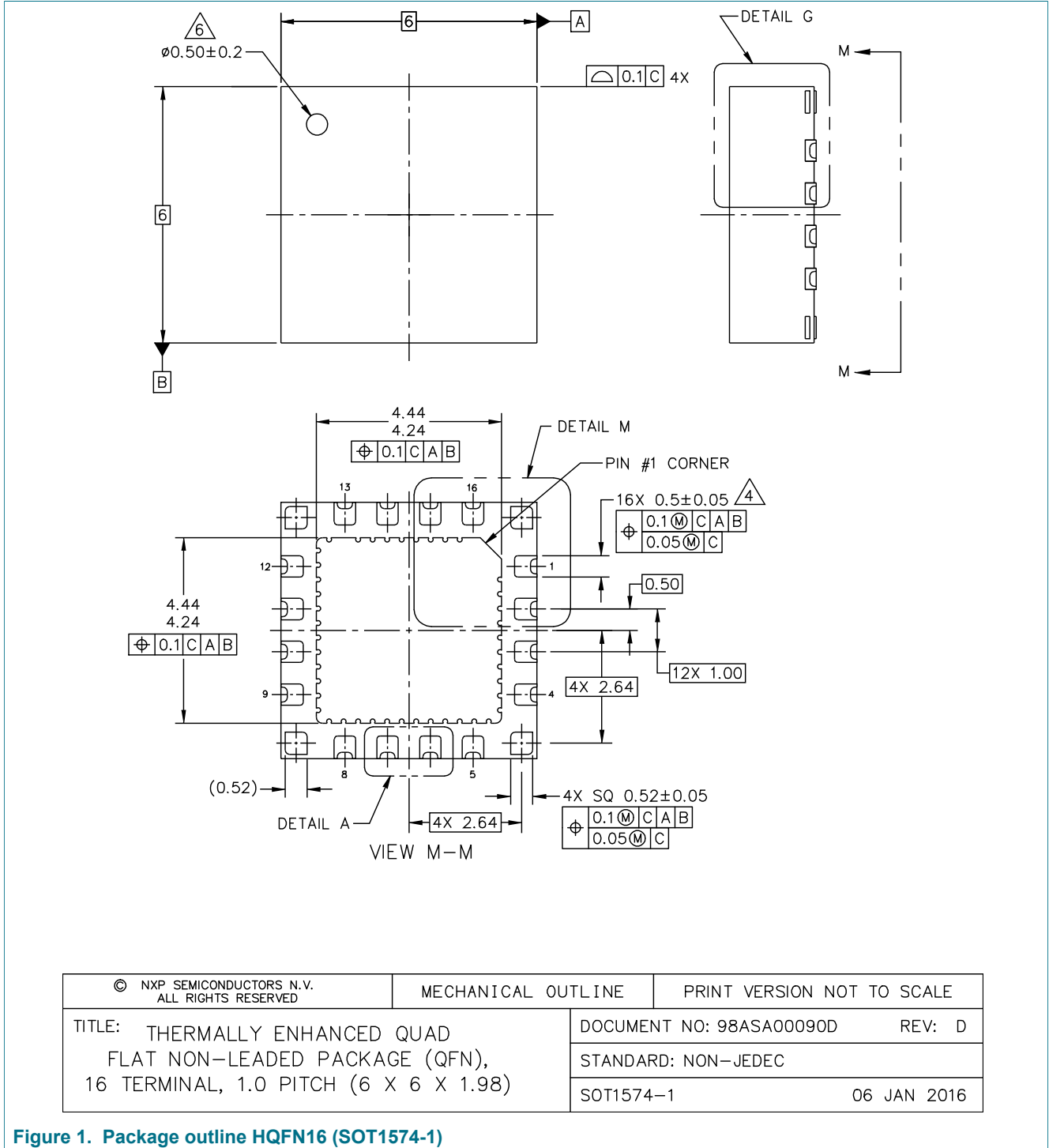


Figure 1. Package outline HQFN16 (SOT1574-1)

plastic, thermally enhanced quad flat non-leaded package; 16 terminals; 1.0 mm pitch; 6 mm x 6 mm x 1.98 mm body

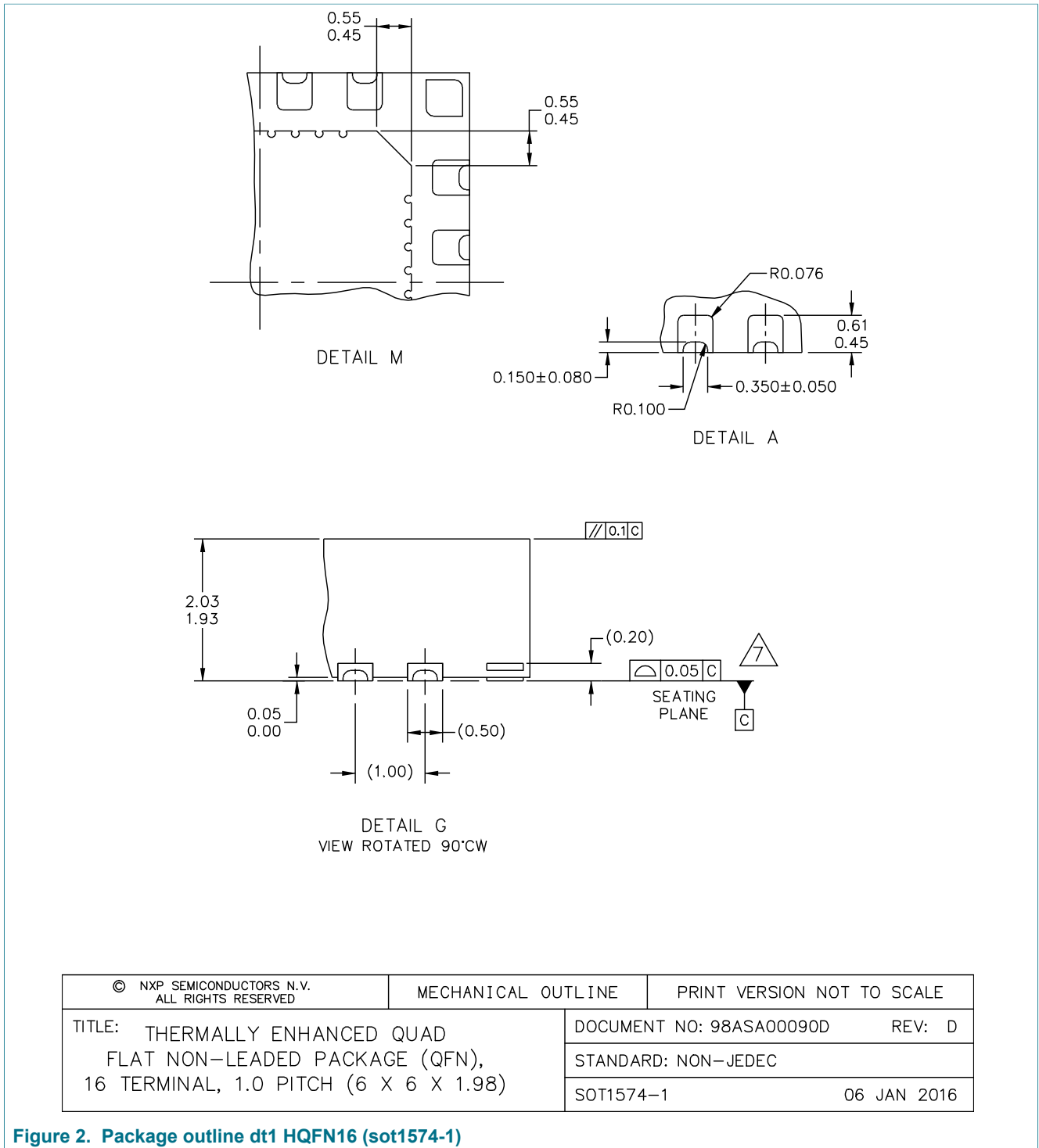


Figure 2. Package outline dt1 HQFN16 (sot1574-1)

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NOTE:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. – 1994.
- 4. THIS DIMENSION APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION b SHOULD NOT BE MEASURED IN THAT RADIUS AREA.
- 5. MAX. PACKAGE WARPAGE IS 0.05 MM.
- 6. PIN #1 ID ON TOP WILL BE LASER MARKED.
- 7. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- 8. THIS IS NON JEDEC REGISTERED PACKAGE.
- 10. MIN. METAL GAP SHOULD BE 0.2 MM

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN), 16 TERMINAL, 1.0 PITCH (6 X 6 X 1.98)		DOCUMENT NO: 98ASA00090D	REV: D
		STANDARD: NON-JEDEC	
		SOT1574-1	06 JAN 2016

Figure 3. Package outline note HQFN16 (sot1574-1)

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### 3 Legal information

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